



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SO-8 (175 °C)					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	40	20 000	200 °C + N2	0	0
HAST	164	16 400	130 °C, 85 % RH	0	0
Pressure Pot	164	15 744	121°, 15 PSIG	0	0
Solder DUNK	110	330	260 °C, 10 s	0	0
Solderability	15	120	883 M2003	0	0
Temp. Cycle	428	317 500	-55 °C to 150 °C	0	0